## CLAIMS

What is claimed is:

1. A hermetic seal for an electronic circuit die comprising:

an inorganic layer for preventing moisture from reaching the electronic circuit die; and

an organic layer outside the inorganic layer for protecting the inorganic layer.

- 2. The apparatus of claim 1 wherein the inorganic layer is adjacent to the organic layer.
- 3. The apparatus of claim 1 further comprising a plastic package.
- 4. The apparatus of claim 3 wherein the inorganic layer is outside the plastic package.
- 5. The apparatus of claim 4 wherein the inorganic layer is inside the plastic package.
  - 6. The apparatus of claim 1 further comprising:
  - a lead; and
  - a wire;

wherein the inorganic layer contacts the lead.

- 7. The apparatus of claim 1 wherein the inorganic layer comprises a material selected from the group consisting of metal oxides, silicon nitride, silicon carbide, aluminum nitride, and diamond-like carbons.
- 8. The apparatus of claim 1 wherein the organic layer comprises a material consisting of para-xylyene, hybrid solgel, and polymeric materials.
- 9. A method of making a hermetic seal comprising:

providing an inorganic layer for protecting from moisture; and

providing an organic layer for protecting the inorganic layer.

- 10. The method of claim 9 further comprising: providing a lead, wherein the lead contacts the inorganic material.
- 11. The method of claim 9 further comprising providing a plastic package.
- 12. The method of claim 11, wherein the plastic package contacts the inorganic layer.

- 13. The method of claim 11, wherein the plastic package contacts the organic layer.
  - 14. A hermetically sealed device comprising: an electronic circuit die;

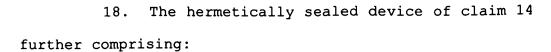
an inorganic layer outside the electronic circuit die; and

an organic layer outside the inorganic material.

- 15. The hermetically sealed device of claim 14 further comprising:
  - a wire; and
  - a lead;

wherein the inorganic layer contacts the lead.

- 16. The hermetically sealed device of claim 14 wherein the inorganic layer comprises a material selected from the group consisting of metal oxides, silicon nitride, silicon carbide, aluminum nitride, and diamond-like carbons.
- 17. The hermetically sealed device of claim 14 wherein the organic layer comprises a material consisting of para-xylyene, hybrid solgel, and polymeric materials.



- a wire;
- a lead; and
- a plastic package.
- 19. The hermetically sealed device of claim 18 wherein the plastic package contacts the inorganic layer.
- 20. The hermetically sealed device of claim 18 wherein the plastic package contacts the organic layer.
- 21. The hermetically sealed device of claim 14 wherein the inorganic layer encloses the electronic circuit die.